

## APPENDIX

1. (~~Twice~~ Three Times Amended) A substrate for semiconductor apparatus, comprising:

a substrate main body having ~~a delineated mounting surface~~ a first surface for mounting the semiconductor device, a second surface and a plurality of through-holes;

a plurality of leads formed on the ~~mounting~~ first surface, the plurality of lead ~~radially~~ leads extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections formed on the second surface, each conduction section defining at least part of an external terminal ~~with substantially rectangular contour lines~~, the conduction sections being electrically connected to the leads via the plurality of through-holes, ~~wherein the substrate main body includes a plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and the through-holes are arranged corresponding to the respective leads such that as the substrate main body that is cut along predetermined through-holes, allows remaining through-holes of connected to the substrate main body respective leads to define the conduction sections.~~ ✓

3. (Twice Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections ~~are formed on a surface opposite of a mounting surface of the semiconductor device and~~ are electrically connected to the leads through the through-holes.

4. (Twice Amended) The substrate for semiconductor apparatus of claim 1, wherein the substrate main body has ~~a~~ the plurality of through-holes for each of the leads, and the conduction sections ~~are formed on a surface opposite of the mounting surface of the device and~~ are electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.

7. ~~(Three~~Four Times Amended) A semiconductor apparatus, comprising:

a semiconductor device having a plurality of electrodes;

a substrate main body; having a first surface for mounting the semiconductor device, a second surface and a plurality of through-holes;

a plurality of leads formed on the ~~substrate main body~~ first surface, the plurality of leads ~~radially~~ extending from a peripheral area toward a central area of the substrate main body; and

a plurality of conduction sections formed on the ~~substrate main body with substantially rectangular contour lines~~ second surface, one of the conduction sections defining an external terminal, the conduction sections being electrically connected to the leads, ~~and one of the conduction sections defining an external terminal, wherein the substrate main body includes a~~ through the plurality of through-holes, internal surfaces of the through-holes are conductive and connected to respective leads, and the through-holes are arranged corresponding to the respective leads such that as the substrate main body that is cut along predetermined through-holes, allows remaining through-holes of the substrate main body respective leads to define the conduction sections.

9. (Amended) The semiconductor apparatus of claim 7, wherein the substrate main body defines a central area and has one through-hole on the side of the central area for each of the leads, and the conduction sections ~~are formed on a surface opposite of a mounting surface of the semiconductor device and~~ are electrically connected the leads through the through-holes.

10. (Amended) The semiconductor apparatus of claim 7, wherein the substrate main body has ~~a~~ the plurality of through-holes for each of the leads, and the conduction sections ~~are formed on a surface opposite of the mounting surface of the device and~~ are



electrically connected to each corresponding one of the leads through a predetermined one of the through-holes.